

Title (en)  
PROCESS FOR THE NON-GALVANIC TIN PLATING OF COPPER OR COPPER ALLOYS

Title (de)  
VERFAHREN ZUR STROMLOSEN VERZINNUNG VON KUPFER ODER KUPFERLEGIERUNGEN

Title (fr)  
PROCEDE DESTINE A L'ETAMAGE NON GALVANIQUE DU CUIVRE OU D'ALLIAGES DE CUIVRE

Publication  
**EP 1230034 A1 20020814 (EN)**

Application  
**EP 00978519 A 20001109**

Priority  
• DE 19954613 A 19991112  
• US 0030983 W 20001109

Abstract (en)  
[origin: WO0134310A1] The invention describes a process for non-galvanic tin plating of copper and copper alloys by precipitation of tin from methanesulphonic acid and tin-containing electrolytes, containing a complexing agent. In describing a process by which a durable tin layer which can be soldered is created, which, at the same time, prevents liberation of the base material, this invention discloses that the electrolytes have at least one foreign metal added to form a diffusion barrier in the tin layer.

IPC 1-7  
**B05D 1/18**

IPC 8 full level  
**B05D 7/14** (2006.01); **C23C 18/31** (2006.01); **C23C 18/48** (2006.01)

CPC (source: EP)  
**C23C 18/31** (2013.01); **C23C 18/48** (2013.01)

Citation (third parties)  
Third party :  
• JP H09302476 A 19971125 - DAIWA KASEI KENKYUSHO  
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• DR. MANFRED JORDAN: "The Electrodeposition of Tin and its Alloys", March 1992, EUGEN G. LEUZEN PUBLISHERS, ISBN: 3-87480-118-7, article "Whiskers", XP003025396

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)  
**WO 0134310 A1 20010517**; AT E480340 T1 20100915; AU 1597501 A 20010606; CN 1192125 C 20050309; CN 1387465 A 20021225; DE 19954613 A1 20010517; DE 60044943 D1 20101021; EP 1230034 A1 20020814; EP 1230034 A4 20030108; EP 1230034 B1 20100908; JP 2003514120 A 20030415; JP 4084569 B2 20080430

DOCDB simple family (application)  
**US 0030983 W 20001109**; AT 00978519 T 20001109; AU 1597501 A 20001109; CN 00815462 A 20001109; DE 19954613 A 19991112; DE 60044943 T 20001109; EP 00978519 A 20001109; JP 2001536299 A 20001109